

MSKSEMI

SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT



PLED

Product data sheet

1.1 Technology Data	Symbol		Value	Unit
Maximum allowable continuous AC voltage at 50-60Hz	V_{RMS}		18	V
Maximum allowable continuous DC voltage	V_{DC}		24	V
Varistor voltage measured * ₁	V_V		100~150	V
Typical capacitance value measured at 1MHz	C		0.15	pF
Typical capacitance value tolerance			+80-20	%
Maximum ESD allowable clamping Voltage* ₂	V_{CLAMP}	<	240	V
Leakage current at V_{DC} * ₃ (At initial state)	I_{LDC}	<	0.1	uA
Leakage current at V_{DC} * ₃ (After ESD Test)	I_{LDCA}	<	2	uA

1.2 Reference Data

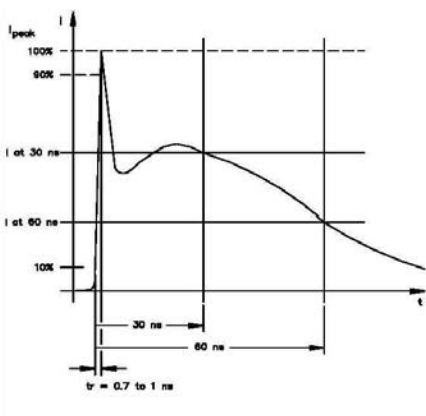
Response time	T_{rise}	<	0.5	ns
Operation ambient temperature			-50~ +85	°C
Storage temperature			-50~+125	°C
ESD testing	IEC61000-4-2		Level 4	

1.3 Other Data

Body			ZnO	
End termination			Ag/Ni/Sn	
Packaging			Reel	
Complies with Standard			IEC61000-4-2	
Complies with RoHs Standard			Yes	
Lead Content		<	1000	ppm
Marking			None	

Notes :

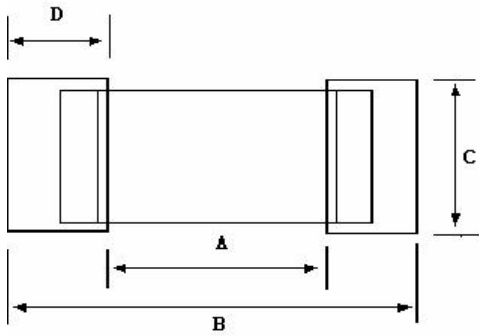
- * 1 The varistor voltage was measured at 1 mA current
- * 2 The Clamping voltage was measured at 8*20 us standard current.
- * 3 The Leakage current was measured at working voltage.
- * 4 The Energy only for customer reference.
- * 5 The components shall be employed within 1 year, in the nitrogen condition.



SEVERITY LEVEL	AIRDIRCHARGE	DIRECT DISCHARGE
1	2 KV	2 KV
2	4 KV	4 KV
3	8 KV	6 KV
4	15 KV	8 KV

IEC 61000-4-2 Compliant ESD Current Pulse Waveform

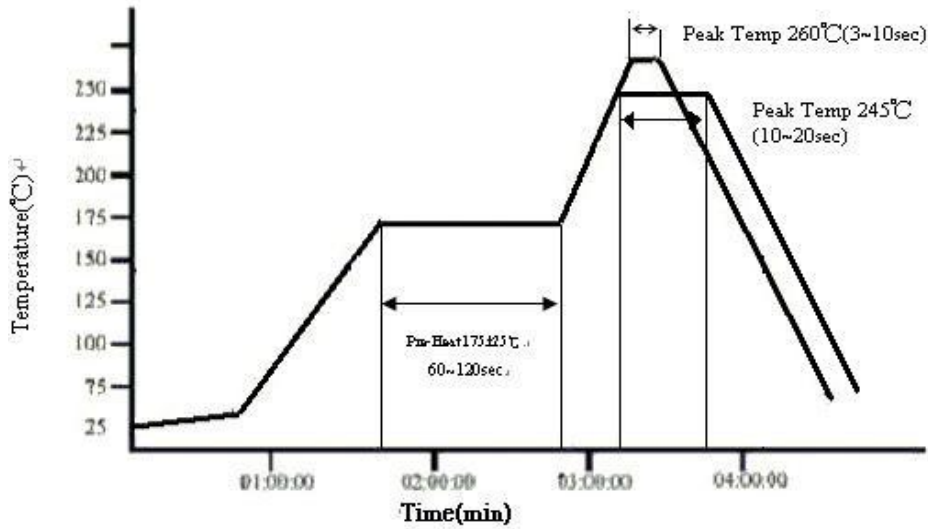
PACKAGE MECHANICAL DATA



0603

Dimension	(Unit : mm)	
	Min.	Max.
A	0.9	1.2
B	2.7	3.2
C	0.7	1.0
D	0.9	1.2

The IR reflow and temperature of Soldering for Pb Free



☆ IR reflow Pb Free Process suggestion profile

- (1) The solder recommend is Sn96.5/Ag 3.5 of 120 to 150 μ m
- (2) Ramp-up rate (217°C to Peak) + 3°C/second max
- (3) Temp. maintain at 175 \pm 25°C 180 seconds max
- (4) Temp. maintain above 217 °C 60-150 seconds

REEL SPECIFICATION

P/N	PKG	QTY
MLSEP24B-0603	0603	4000

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